

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
Contact Info: [ti.com/support](https://ti.com/support)  
Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
Created on: 06/10/2022

Details for "TPSS1103DRCR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TPS51103DRCR	NIPDAU	Level-2-260C-1 YEAR	TI MALAYSIA A/T	DRC   10	3.00X3.00X0.90	24.6

**\*Total Device Mass**  
The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.049955	99.997998	999980	0.202954	2030
Precious Metals	Silver	7440-22-4	0.000001	0.002002	20	0.000004	0
Sub-Total			0.049956	100	1000000	0.202958	2030
Die Attach Adhesive							
Other Inorganic Materials	Silica	7631-86-9	0.005547	1.999892	19999	0.022536	225
Precious Metals	Silver	7440-22-4	0.191382	69.000054	690001	0.777535	7775
Thermoplastics	Epoxy	85954-11-6	0.080436	29.000054	290001	0.32679	3268
Sub-Total			0.277365	100	1000000	1.126862	11269
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	11.18349	99.25	992500	45.435602	454356
Other Nonferrous Metals and Alloys	Chromium	7440-47-3	0.029297	0.260002	2600	0.119026	1190
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.02817	0.25	2500	0.114447	1144
Zinc and Its Alloys	Zinc	7440-66-6	0.027043	0.239998	2400	0.109869	1099
Sub-Total			11.268	100	1000000	45.778944	457789
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.193094	95.120197	951202	0.784491	7845
Precious Metals	Gold	7440-57-5	0.001583	0.779803	7798	0.006431	64
Precious Metals	Palladium	7440-05-3	0.008323	4.1	41000	0.033814	338
Sub-Total			0.203	100	1000000	0.824736	8247
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	10.777518	90.500005	905000	43.786244	437862
Other Plastics and Rubber	Carbon Black	1333-86-4	0.059544	0.499998	5000	0.241912	2419
Thermoplastics	Epoxy	85954-11-6	1.071797	8.999997	90000	4.354432	43544
Sub-Total			11.908859	100	1000000	48.382587	483826
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.906756	100	1000000	3.683913	36839
Sub-Total			0.906756	100	1000000	3.683913	36839
Total			24.613936			100	1000000

**Important Note**  
The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.  
[See Glossary of Terms for more details.](#)

**Important Part Information**  
There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**  
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**  
TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**  
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Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
Created on: 06/10/2022

**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.